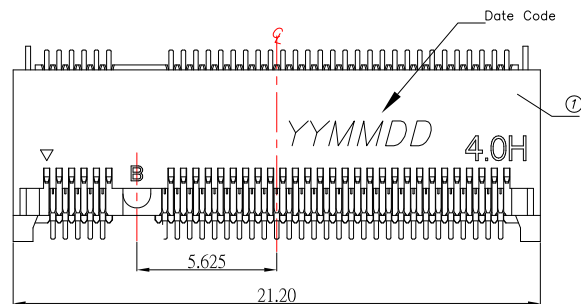
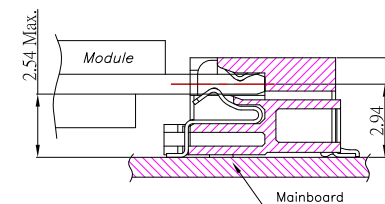


How to mate and unmate
Mate: ① - ② - ③
Unmate: ④



NGF-40S1B-xx-S273

鍍層厚度:

COLOR:

Blank: 1u"

2: 15u"

3: 30u"

Black: B

White: W

1.SPECIFICATION:

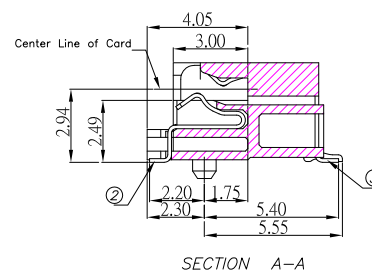
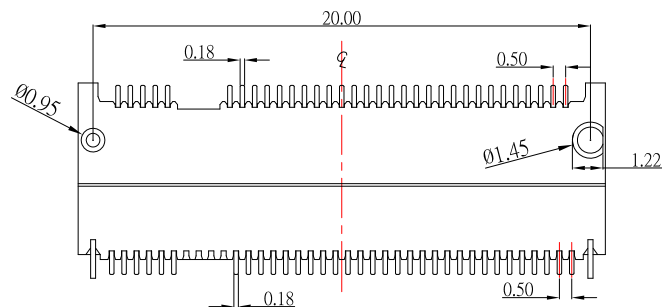
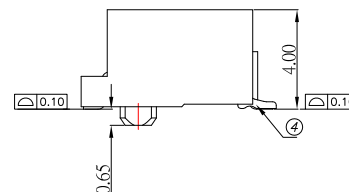
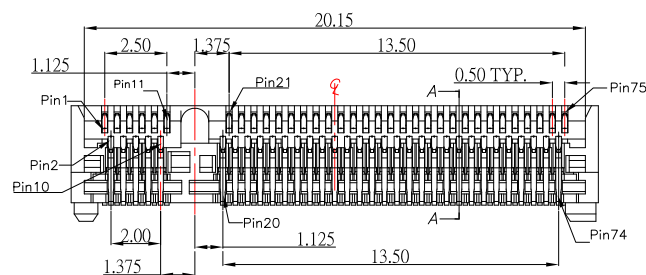
- 1.1 Current Rate: 0.5 A
- 1.2 Voltage Rate: 50V AC
- 1.3 Insulator Resistance: 500 MΩ Min
- 1.4 Dielectric Strength: 300V AC
- 1.5 Contact Resistance: 20mΩ Max
- 1.6 Mating Force: 20N Max
- 1.7 Unmating Force: 20N Max

2.MATERIAL:

- 2.1 Housing: LCP,UL94V-0
- 2.2 Contact: Phosphor Bronze
- 2.3 Leg: Brass

3.Finish:

- 3.1 Contact: Plated Gold in Mating Area ;
Tin Plated on Solder Balls ;
Nickel under plated overall
- 3.2 Leg: Tin Plated on Solder Balls
Nickel under plated overall



 東莞市高迪電子有限公司
DONG GUAN GAO DI ELECTRONICS CO., LTD

TOLERANCE UNLESS OTHERWISE STATED:
Up to 5 ±0.2
Above 5 ~ 15 ±0.3
Above 15 ~ 30 ±0.4
Above 30 ~ 50 ±0.5
Angle ±0.3°

3RD.
ANGEL'S



UNITS

MM

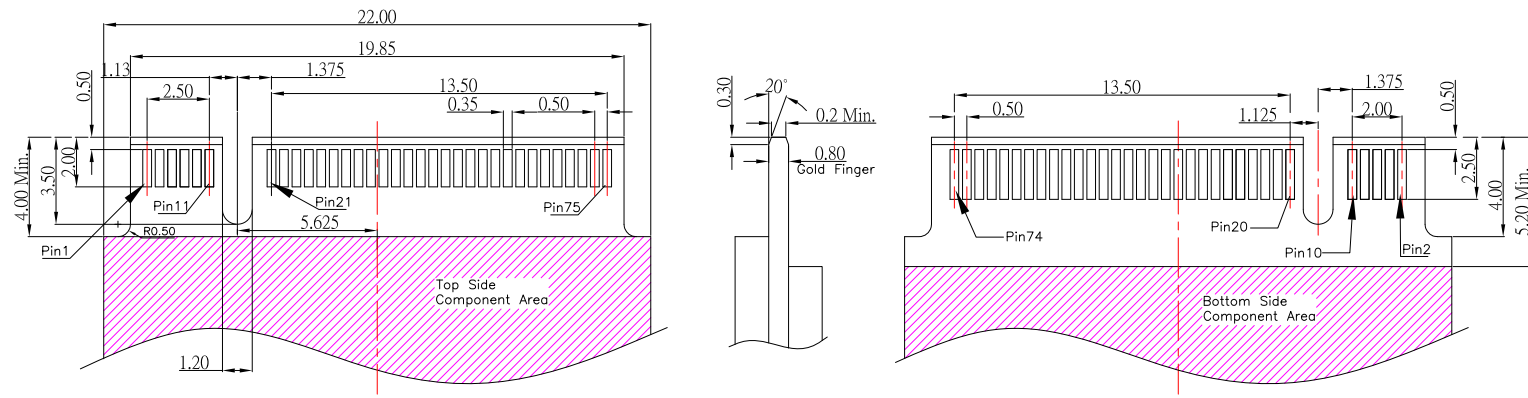
DRAWN BY: Jack Lu
CHECKED BY: Jacky Chen
APPROVED BY: Tony Kao
DATE: 05/04/16
DATE: 05/04/16
DATE: 05/04/16

MAT'L
FINISH
SCALE
SHEET NO.

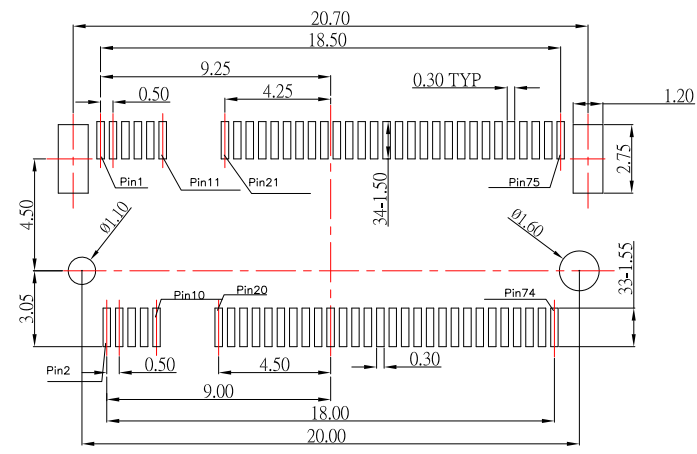
TITLE
MODLE
DWG NO.
PART NO.

CONNECTOR
NGFF SOCKET 板上4.0H 正向 B KEY
NGF-40S1B-xx-S273
NGF-40S1B-xx-S273
SIZE: A4
VER: R1

ITEM NO.	DESCRIPTION	DRAWN	DATE
1	更新料號及MODLE	Jack	050416



Recommended Mould Finger Layout



Recommended PCB Layout(Top View)



TOLERANCE UNLESS OTHERWISE STATED :
Up to 5 ±0.2
Above 5 ~ 15 ±0.3
Above 15 ~ 30 ±0.4
Above 30 ~ 50 ±0.5
Angle ±0.3°

3RD. ANGEL'S

UNITS MM

DRAWN BY:	DATE	MAT'L	TITLE	CONNECTOR
Jack Lu	05/04/16			
CHECKED BY:	DATE	FINISH	MODLE	NGFF SOCKET 板上4.0H 正向 B KEY
Jacky Chen	05/04/16			
APPROVED BY:	DATE	SCALE	DWG NO.	SIZE
Tony Kao	05/04/16	1 : 1	NGF-40S1B-xx-S273	A4
		SHEET NO.	PART NO.	VER
		2 of 2	NGF-40S1B-xx-S273	R1